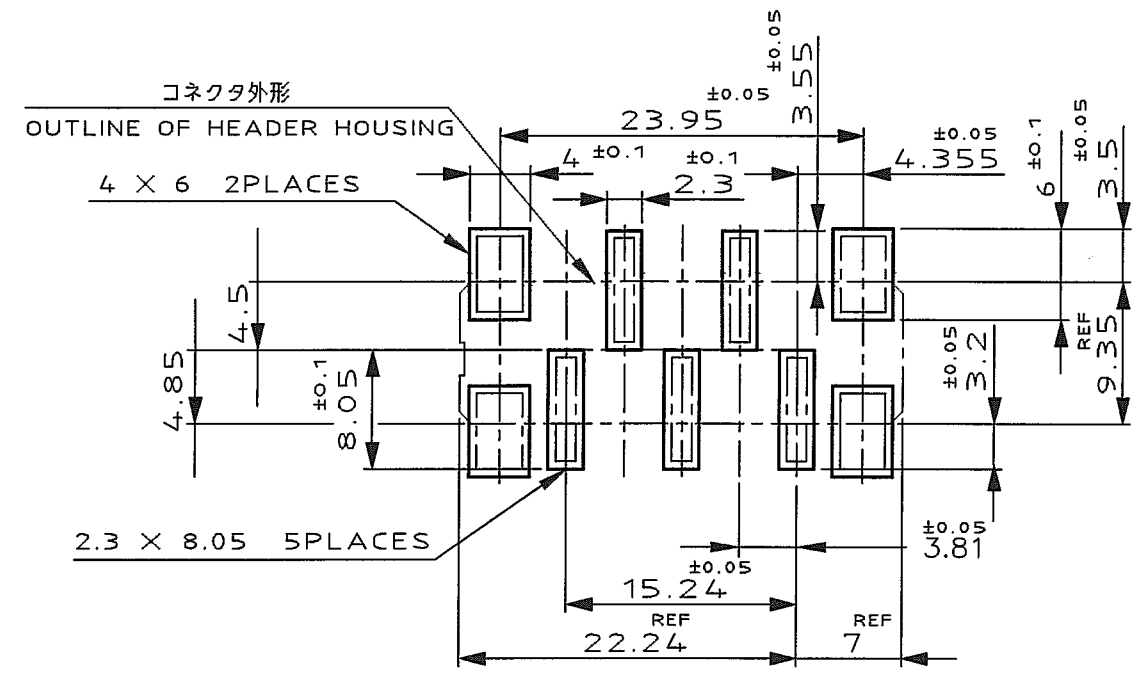
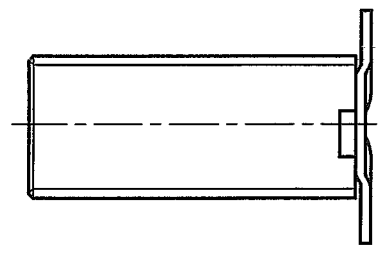
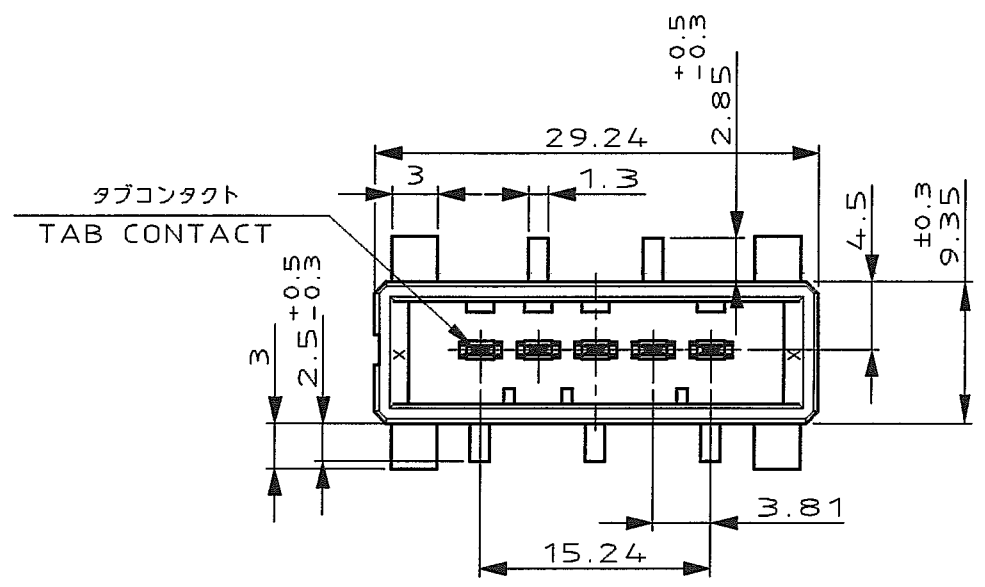
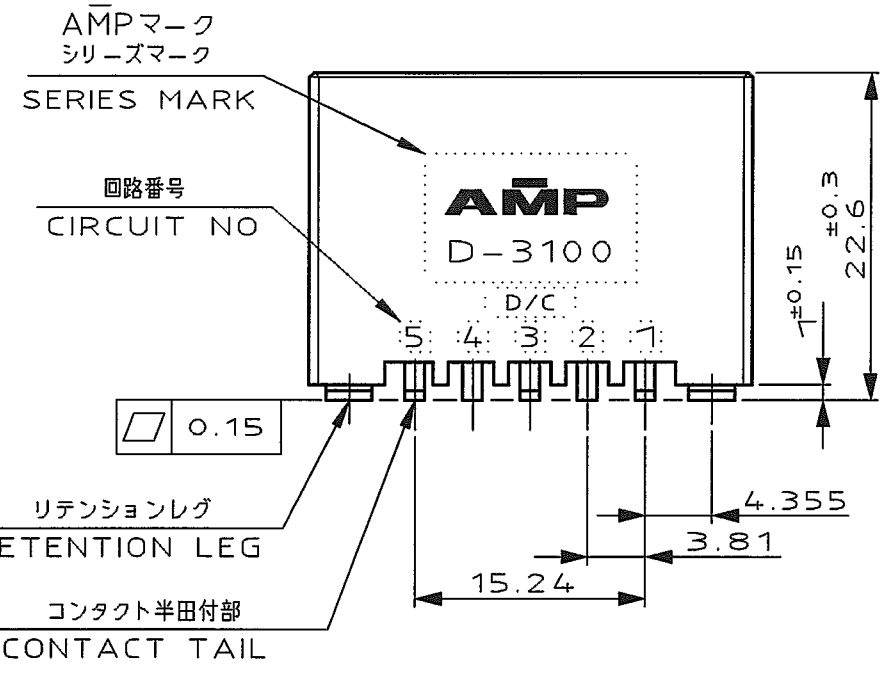


NUMBER 177665
 METRIC
 PROJ NO.392-610
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT
 PRINT DIST
 AMP-J
 REV.10/83



推奨基板取付け寸法
(非累積公差)
(コネクタ搭載面)

RECOMEND BOARD PATTERN
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)



NOTES

1. MATERIAL:HOUSING:GLASS FILED THERMO PLASTIC,UL94V-0
CONTACT:COPPER ALLOY
RETENTION LEG:COPPER ALLOY
2. FINISH(CONTACT AREA):0.38μmMIN GOLD PLATING OVER Ni PLATING
3. FINISH(CONTACT AREA):0.76μmMIN GOLD PLATING OVER Ni PLATING
4. FINISH(RETENTION LEG): TIN PLATED (SOLDER TYING) OVER NICKEL

注記

1. 材料:ハウジング:ガラス入り熱可塑性樹脂,UL94V-0
コンタクト:銅合金
リテンションレグ:銅合金
2. めっき:コンタクト接触部:ニッケル下地の上に金めっき0.38μmMIN
3. めっき:コンタクト接触部:ニッケル下地の上に金めっき0.76μmMIN
4. めっき:リテンションレグとコンタクト半田付部:ニッケル下地の上にスズめっき

4	3	1-177665-3
4	2	1-177665-2
(FINISH)		製品番号 (PART NO.)

A	REVISED(FJD0-0039-03)	TS	SM	4/2/93	
0	RELEASED (FJ00-0284-93)	NM	SM	9/30/93	
LTR	REVISION RECORD	DR	CHK	DATE	

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tyco
Electronics

Tyco Electronics AMP K.K.
Kawasaki, Japan

WIRE RANGE	INSULATION DIA	NAME
mm²(AWG -)	- mmφ	5 POS SINGLE ROW SMT TYPE VERTICAL HDR ASS'Y FOR DYNAMIC 3100
MATERIAL SEE NOTE 注記参照	FINISH SEE NOTE 注記参照	一般公差 (GENERAL TOLERANCE)
DR. N. Matsubara 20 SEP 93	DE. N. Matsubara 20 SEP 93	10MF : ±0.2
CHK. S. MANABE 30 SEP 93	APP. S. MANABE 30 SEP 93	10MF 30MF : ±0.3
		30MF 100MF : ±0.4
		角 度 : ±3'
		SIZE LOC NUMBER
		A3 J C=177665
		SCALE REV. SHEET
		2-1 A 1 OF 1

(CUSTOMER DRAWING) 顧客用図面